

IN THE SPECIFICATION

On page 15, bridging page 16, amend paragraph [00034] to read as follows:

Typical chip slapper detonators include a ceramic substrate with a deposited film such as copper etched into shaped wide area conductive lands and a narrow bridge portion extending between such lands. A dielectric coating, such as a polyimide, KAPTON™ (i.e., a polyimide film developed which can remain stable in a wide range of temperatures) ~~Kapton~~ or PARALENE™ (i.e., a unique series of polymers based on paraxylene) ~~Parylene~~, is applied over the bridge portion, wherein a small section (i.e., a flying plate) of this dielectric is accelerated away from the substrate and towards an explosive when an applied voltage (e.g., greater than about 2000 volts) vaporizes the narrow bridge portion. The shock of such a flying plate detonates the explosive. By utilizing modified chip slappers that can initiate with less than 50 mj of electrical energy, the present invention's associated components (such as capacitors, switches, etc.) overall current, voltage, and thus size requirements can be reduced, which leads to lower component costs and allows the design arrangement of such units in a perforating gun to be less stringent.